1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: I_{F(AV)} ≤ 2 A
- Reverse voltage: V_R ≤ 100 V
- Low forward voltage: V_F = 710 mV
- High power capability due to clip-bonding technology
- Extremely low leakage current
- High temperature T_i≤ 175 °C
- Small and flat lead SMD plastic package
- AEC-Q101 qualified
- · Capable for reflow and wave soldering

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|--------------------|-------------------------|---|-----|-----|-----|------|
| I _{F(AV)} | average forward current | δ = 0.5 ; f = 20 kHz; $T_{sp} \le 165$ °C; square wave | - | - | 2 | Α |
| V _R | reverse voltage | T _j = 25 °C | - | - | 100 | V |
| V _F | forward voltage | I_F = 2 A; t_p ≤ 300 μs; δ ≤ 0.02 ; T_j = 25 °C | - | 710 | 770 | mV |
| I _R | reverse current | $V_R = 100 \text{ V}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 70 | 300 | nA |



5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|---------------------|----------------|
| 1 | K | cathode[1] | | 1 🔂 2 |
| 2 | A | anode | 1 2 2 CFP5 (SOD128) | sym001 |

^[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | | |
|---------------|---------|--|---------|--|--|--|
| | Name | Description | Version | | | |
| PMEG10020AELP | CFP5 | plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body | SOD128 | | | |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|---------------|--------------|
| PMEG10020AELP | DM |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|--------------------|-------------------------------------|---|-----|-----|------|------|
| V_R | reverse voltage | T _j = 25 °C | | - | 100 | V |
| l _F | forward current | T _{sp} = 160 °C; δ = 1 | | - | 2.83 | Α |
| I _{F(AV)} | average forward current | δ = 0.5 ; f = 20 kHz; $T_{amb} \le 100 ^{\circ}\text{C}$; square wave | [1] | - | 2 | А |
| | | δ = 0.5 ; f = 20 kHz; $T_{sp} \le 165$ °C; square wave | | - | 2 | А |
| I _{FSM} | non-repetitive peak forward current | t_p = 8 ms; $T_{j(init)}$ = 25 °C; square wave | | - | 50 | А |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | [2] | - | 750 | mW |
| | | | [3] | - | 1250 | mW |
| | | | [1] | - | 2500 | mW |
| Tj | junction temperature | | | - | 175 | °C |
| T _{amb} | ambient temperature | | | -55 | 175 | °C |
| T _{stg} | storage temperature | | | -65 | 175 | °C |

- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al₂O₃, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit |
|-----------------------|--|-------------|------------|-----|-----|-----|------|
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | [1] [2] | - | - | 200 | K/W |
| | | | [1] [3] | - | - | 120 | K/W |
| | | | [1] [4] | - | - | 60 | K/W |
| R _{th(j-sp)} | thermal resistance from junction to solder point | | <u>[5]</u> | - | - | 12 | K/W |

^[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

^[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

^[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

^[5] Soldering point of cathode tab.

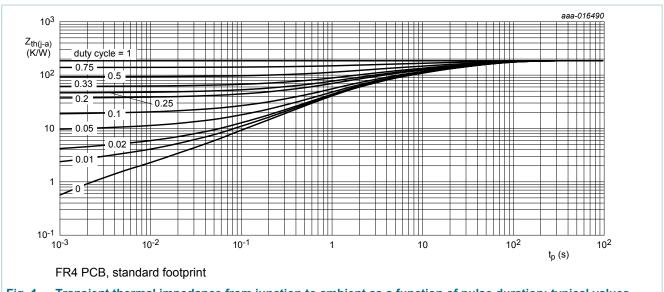


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

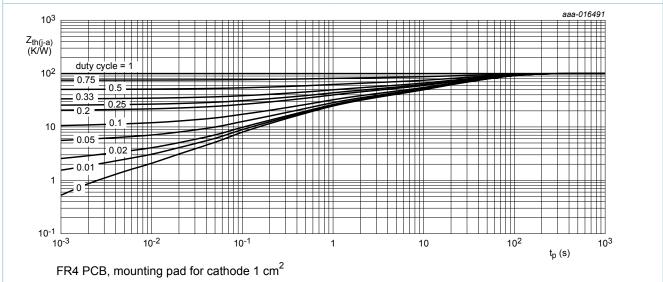
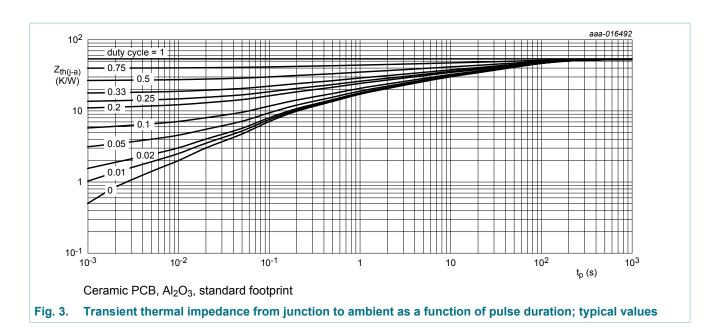


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit | |
|----------------|-------------------------------|---|---|-----|------|------|----|
| $V_{(BR)R}$ | reverse breakdown voltage | I_R = 1 mA; t_p = 300 μs; δ = 0.02 ; T_j = 25 °C | 100 | - | - | V | |
| V _F | V _F | forward voltage | $I_F = 0.1 \text{ A}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 470 | 520 | mV |
| | | $I_F = 0.5 \text{ A}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 580 | 630 | mV | |
| | | $I_F = 0.7 \text{ A}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 610 | 670 | mV | |
| | | I_F = 1 A; $t_p \le 300 \mu s$; δ ≤ 0.02 ; T_j = 25 °C | - | 650 | 710 | mV | |
| | | $I_F = 1.6 \text{ A}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 690 | 750 | mV | |
| | | $I_F = 2 \text{ A}; t_p \le 300 \text{ μs}; \delta \le 0.02 ;$ $T_j = 25 \text{ °C}$ | - | 710 | 770 | mV | |
| | | $I_F = 2 \text{ A}; t_p \le 300 \text{ μs}; δ \le 0.02 ;$ $T_j = 125 \text{ °C}$ | - | 575 | 650 | mV | |
| I _R | reverse current | $V_R = 10 \text{ V}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 10 | - | nA | |
| | | $V_R = 60 \text{ V}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 25 | - | nA | |
| | | $V_R = 100 \text{ V}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 25 ^{\circ}\text{C}$ | - | 70 | 300 | nA | |
| | | $V_R = 100 \text{ V}; t_p \le 300 \mu\text{s}; \delta \le 0.02 ;$ $T_j = 125 ^{\circ}\text{C}$ | - | 120 | 1000 | μA | |
| C_d | diode capacitance | V _R = 1 V; f = 1 MHz; T _j = 25 °C | - | 135 | - | pF | |
| | | V _R = 4 V; f = 1 MHz; T _j = 25 °C | - | 80 | - | pF | |
| | | V _R = 10 V; f = 1 MHz; T _j = 25 °C | - | 50 | - | pF | |
| rr | reverse recovery time | $I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 ^{\circ}\text{C}$ | - | 5 | - | ns | |
| V_{FRM} | peak forward recovery voltage | $I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 °C$ | - | 610 | - | mV | |

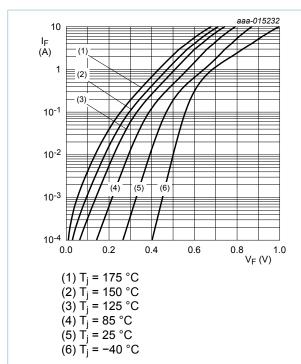


Fig. 4. Forward current as a function of forward voltage; typical values

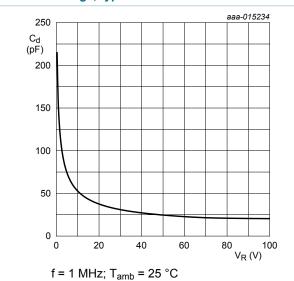


Fig. 6. Diode capacitance as a function of reverse voltage; typical values

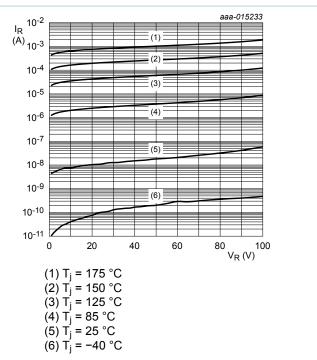
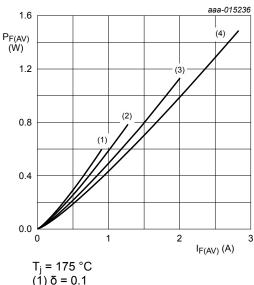
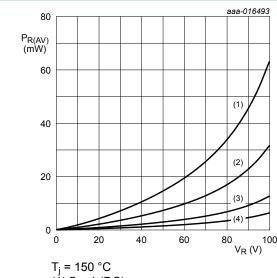


Fig. 5. Reverse current as a function of reverse voltage; typical values



 $T_j = 175 \,^{\circ}\text{C}$ (1) $\delta = 0.1$ (2) $\delta = 0.2$ (3) $\delta = 0.5$ (4) $\delta = 1$

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



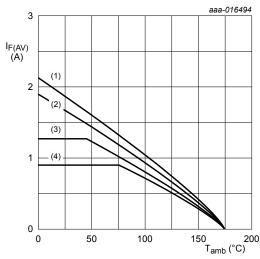
 $(1) \delta = 1 (DC)$

(2) $\delta = 0.5$; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 175 °C

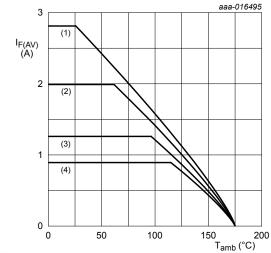
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

 $T_j = 175 \,{}^{\circ}\text{C}$

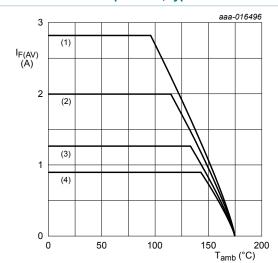
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint

T_i = 175 °C

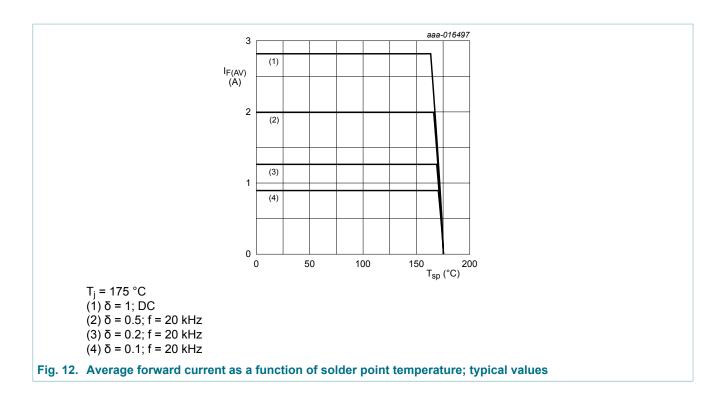
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

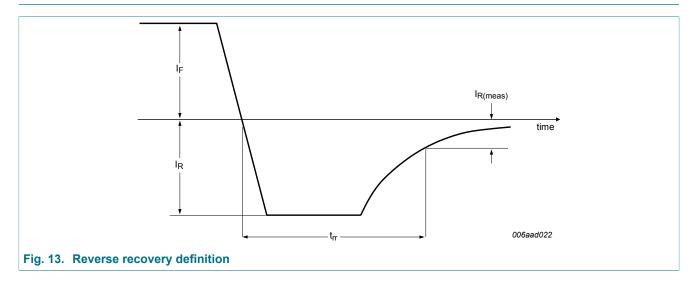
(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

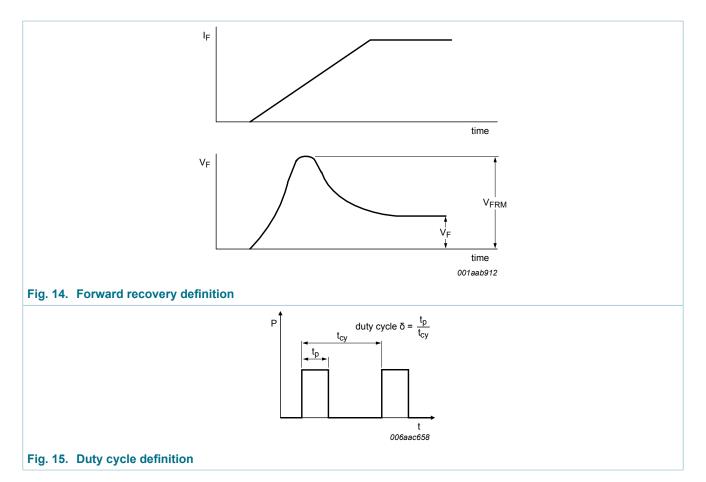
Fig. 11. Average forward current as a function of ambient temperature; typical values



11. Test information



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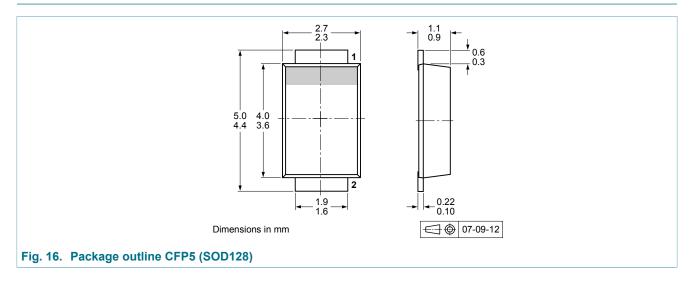


The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

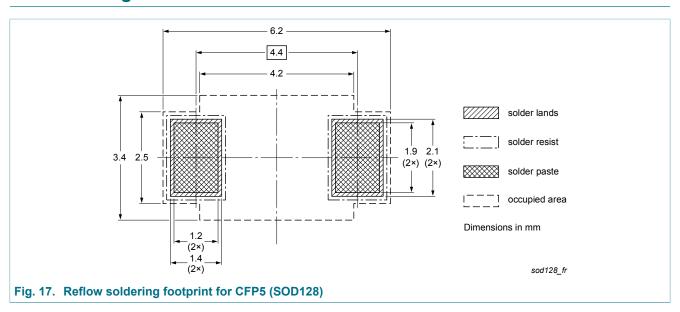
Quality information

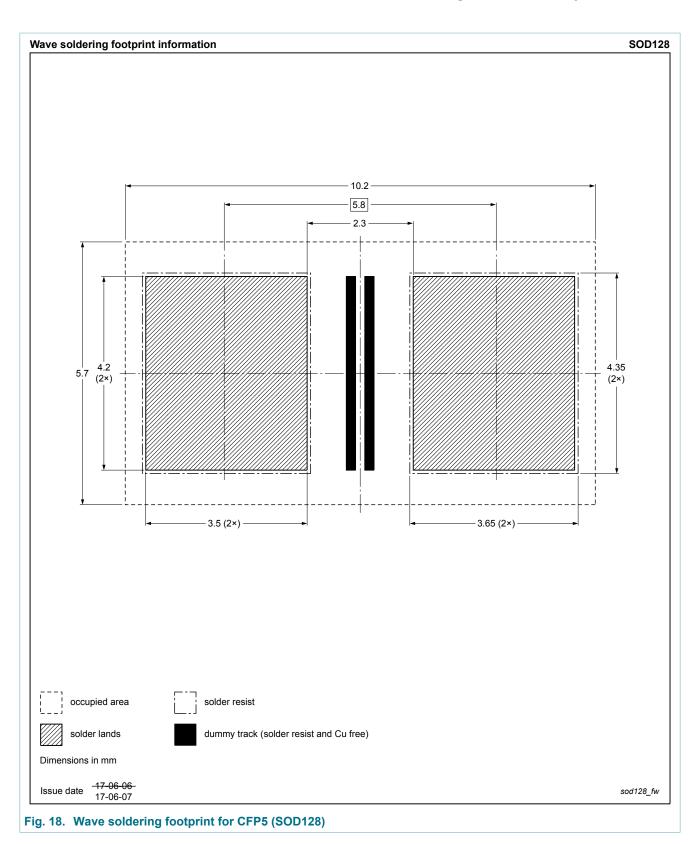
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering





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14. Revision history

Table 8. Revision history

| · · · · · · · · · · · · · · · · · · · | | | | | | | | |
|---------------------------------------|---|--------------------|---------------|-------------------|--|--|--|--|
| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes | | | | |
| PMEG10020AELP v.2 | 20171129 | Product data sheet | - | PMEG10020AELP v.1 | | | | |
| Modifications: | Features and benefits: Capable for reflow and wave soldering added Soldering: Wave soldering footprint added | | | | | | | |
| PMEG10020AELP v.1 | 20150507 | Product data sheet | - | - | | | | |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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PMEG10020AELP

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